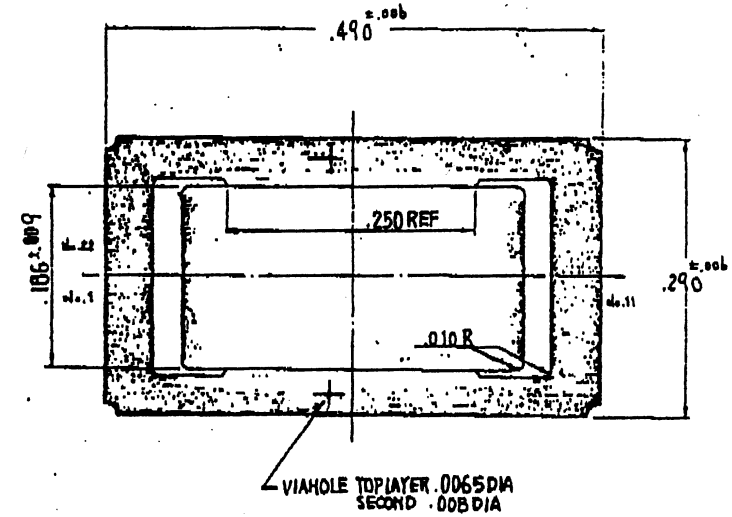
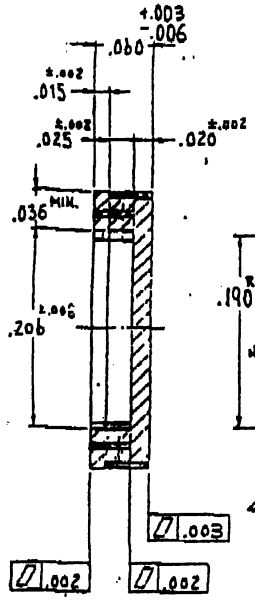
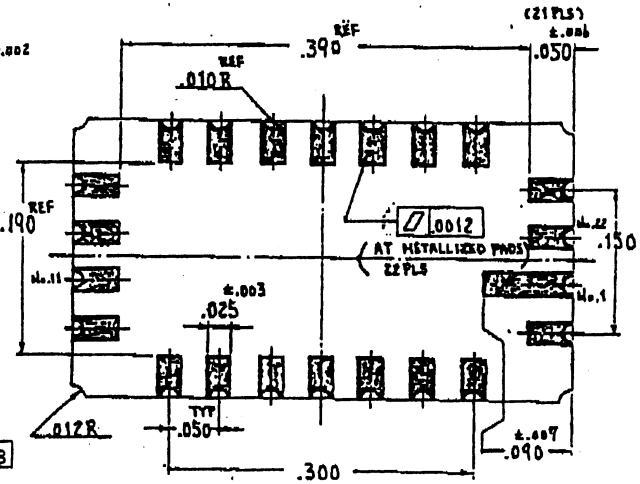
SSM P/N LCC02203

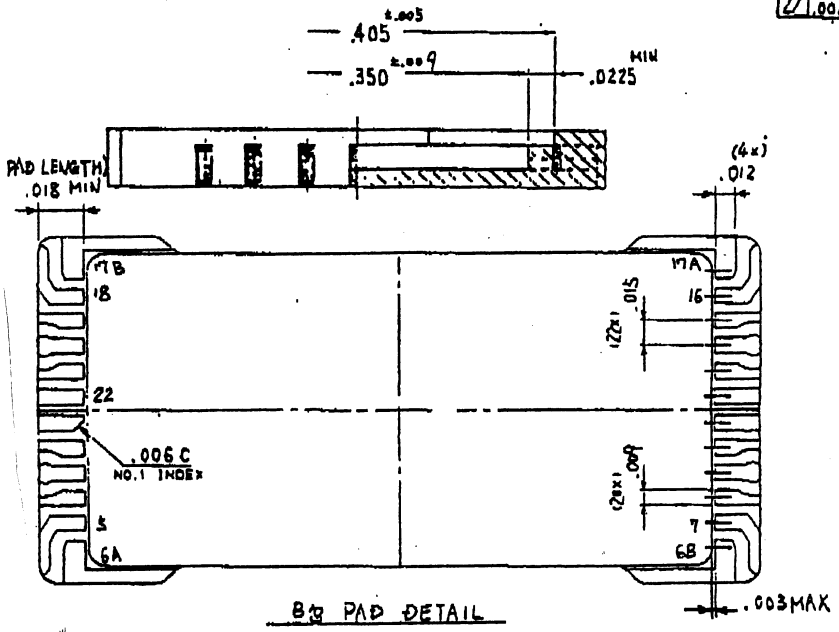
LATEST REVISION'S DISCRIPTION

B CHANGED D/A CAVITY TOLERANCE .350±.009 × .186±.009 WAS .350±.005 × .186±.005









B面 PAD DETAIL

5. NO.11 LEAD TO BE ELECTRICALLY CONNECTED TO THE SEAL RING.

6. PAD NO. 6A AND 6B TO BE ELECTRICALLY CONNECTED TO LEAD NO. 6

7. PAD NO. 17A AND 17B TO BE ELECTRICALLY CONNECTED TO LEAD NO. 17.

NOTES: 1. ELECTRO GOLD 80μ INCHES MIN OVER 80μ INCHES MIN. ELECTRO NICKEL.

2. No.22 LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD.

3. LEAD RESISTANCE 500 mΩ MAX.

B				B RE DRAWING	APR-28-1990
2				A RE DRAWING	APR-23-1990
1	CERAMIC	BLACK ALUMINA		φ NEW DRAWING	MAR-31-1990
Item	Name	Material	Description	Rev. Description	Date

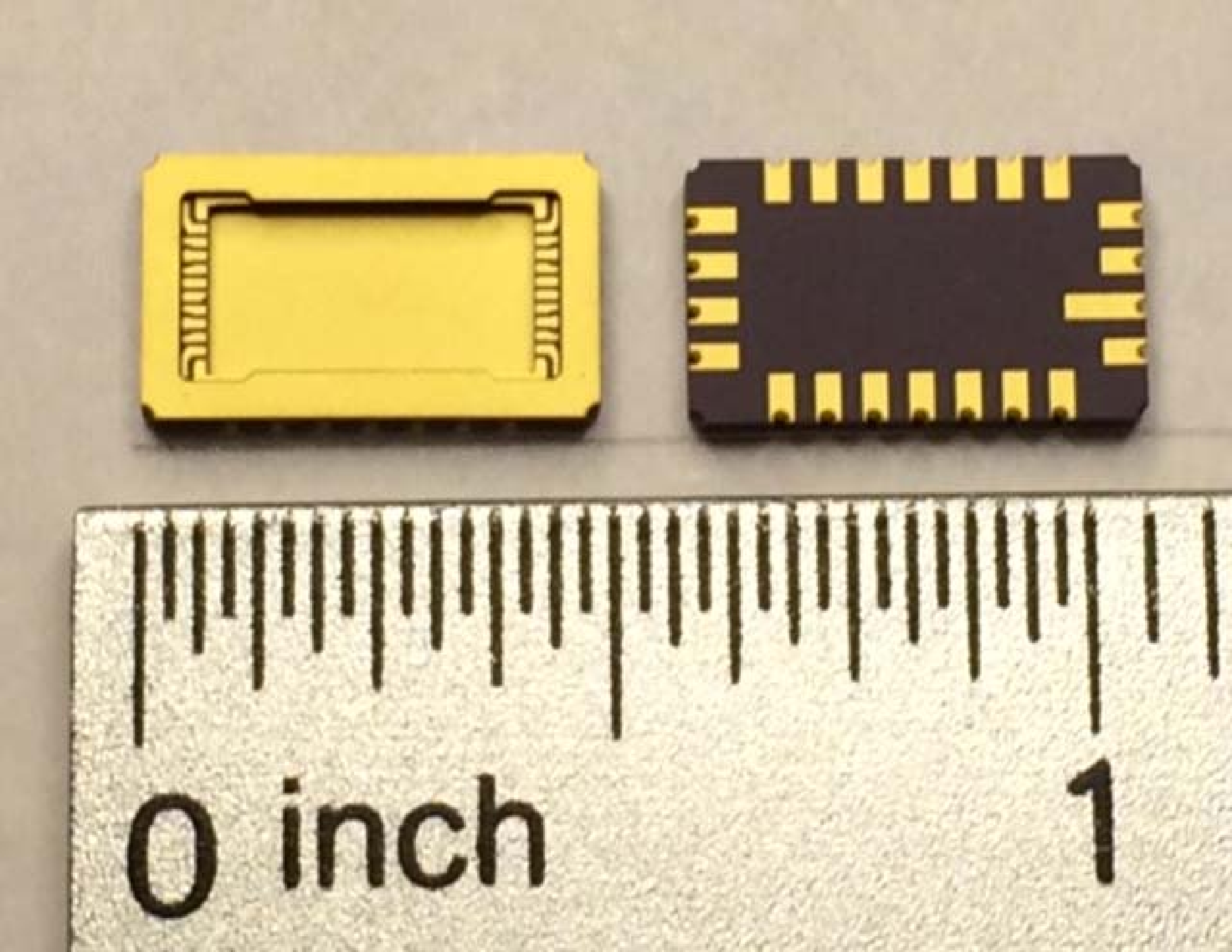
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1%
M. L. T. ± DECIMALS .XX ±.01, ± DECIMALS .XXX ±.005

DRAWN X. Chik
CHECKED
APPROVED
UNIT INCH
SCALE

CUSTOMER
DWG NO.

TITLE 22 LEAD CHIP CARRIER
DWG NO. IRK22F1-5396A
SIZE A-3 (C)

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226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